2SC3975

Silicon NPN triple diffusion planar type

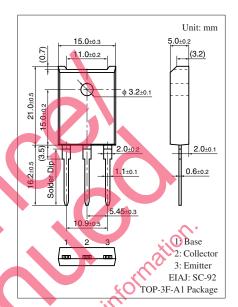
For high breakdown voltage high-speed switching

■ Features

- High-speed switching
- ullet High collector-base voltage (Emitter open) V_{CBO}
- Wide safe operation area
- Satisfactory linearity of forward current transfer ratio h_{FE}
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	800	V	
Collector-emitter voltage (E-B short)	V _{CES}	800	V	
Collector-emitter voltage (Base open)	V _{CEO}	500	V	
Emitter-base voltage (Collector open)	V _{EBO}	8	V	
Base current	I_{B}	5	A	
Collector current	I_{C}	10	A	
Peak collector current	I _{CP}	20	A	
Collector power dissipation	P_{C}	100	W	
$T_a = 25^{\circ}C$		3.0		
Junction temperature	T_j	150	°C	
Storage temperature	T_{stg}	-55 to $+150$	°C	



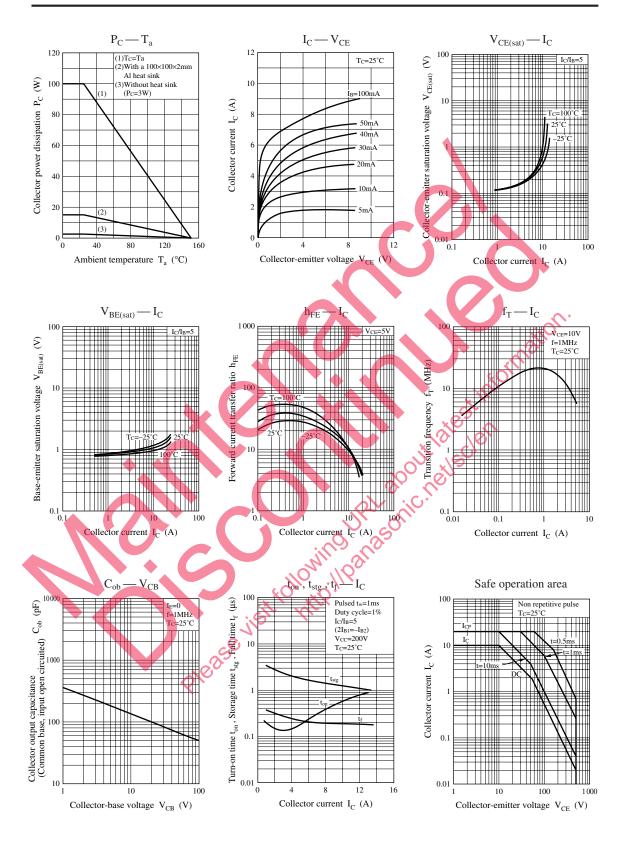
■ Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V_{CEO}	$I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0$	500			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 800 \text{ V}, I_{E} = 0$			100	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 5 \text{ V}, I_C = 0$			100	μΑ
Forward current transfer ratio	h_{EE1}	$V_{CE} = 5 \text{ V}, I_{C} = 0.1 \text{ A}$	15			_
	h_{FE2}	$V_{CE} = 5 \text{ V}, I_{C} = 6 \text{ A}$	8			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 6 \text{ A}, I_B = 1.2 \text{ A}$			1.0	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 6 \text{ A}, I_B = 1.2 \text{ A}$			1.5	V
Transition frequency	f_T	$V_{CE} = 10 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time	t _{on}	$I_C = 6 A$			1.0	μs
Storage time	t _{stg}	$I_{B1} = 1.2 \text{ A}, I_{B2} = -2.4 \text{ A}$			3.0	μs
Fall time	$t_{\rm f}$	$V_{CC} = 200 \text{ V}$			0.3	μs

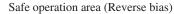
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

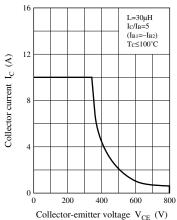
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Panasonic

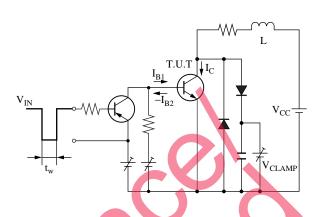


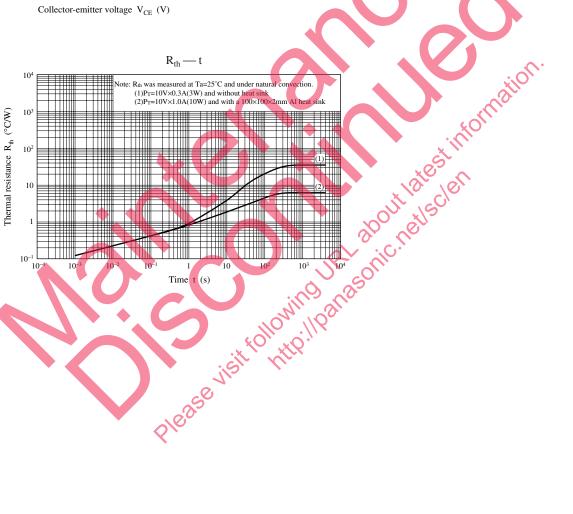
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Safe operation area (Reverse bias) measurement circuit





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